

To: Technology Unit: 2814
Facsimile Number: 703-872-9306

Total Pages Sent 4

From: W. Daniel Swayze, Jr.
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-5633

RECEIVED
CENTRAL FAX CENTER

JUN 08 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by
facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on
the date shown below:


Tommie Chambers6-8-05
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input type="checkbox"/> AMENDMENT (# Pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT (# Month)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> CHANGE IN CORRESPONDENCE
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	<input type="checkbox"/> ADDRESS
<input type="checkbox"/> DIVISIONAL APP'N	<input checked="" type="checkbox"/> REPLY BRIEF
NAME OF INVENTOR(S): Yew	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/612,129 Filing Date: 7/2/2003	
TITLE OF INVENTION: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE	
TI FILE NO.: TI-26239.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6-8-05 DUE: 06/19/2005 ATTY/SECY: WDS/llc	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED
CENTRAL FAX CENTER

Applicant: Yew
Serial No: 10/612,129
Filed: 7/2/2003
For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE

Docket No: TI-26239.1
Examiner: Cao, Phat X.
Art Unit: 2814

JUN 08 2005

REPLY BRIEF

Assistant Commissioner For Patents
Washington, DC 20231

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being
transmitted by facsimile to the U.S. Patent and Trademark
Office at 703-872-9306 on 6-8-05:

Tommy Chambers
Tommy Chambers

Dear Sir:

Responsive to the Examiner's Answer mailed April 19, 2005 in connection with the above identified application, Applicants respectfully submit the following remarks.

TI-26239.1 Page 1

REMARKS

The Examiner alleges on the paragraph bridging pages 7 and 8, the Appellant's arguments have no immediate apparent relevance to the issues presented by the rejection since Appellants cannot show nonobviousness by attacking references individually where the rejection is based upon the combination of references.

Appellants respectfully disagree.

Appellants have shown that both Lee and Lupinski does not disclose or suggest the presently claimed invention including a plurality of contact pads disposed on the first surface of the substrate and the second surface of the substrate being directly attached to the preactivated polymer layer.

Since both of these references do not disclose the above mentioned claimed subject matter, the combination of these references cannot disclose this subject matter and consequently the Examiner's rejection under 35 U.S.C. § 103 is improper.

Additionally, Appellants note that the Examiner has incorrectly listed the reference to Horoshi as 06-629454 and Appellants believe that it should be 06-029454.

Again for the forgoing reasons, Appellants respectfully submit that the Examiner's rejections are improper and requests the Honorable Board to reverse the Examiner's rejections.

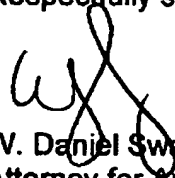
In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant response places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is

respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



W. Daniel Swayze, Jr.
Attorney for Applicant
Reg. No. 34,478

Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265
(972) 917-5633